



深圳市富满电子集团股份有限公司

SHEN ZHEN FINE MADE ELECTRONICS GROUP CO., LTD.

3060K (文件编号: S&CIC1695)

## N-Channel Trench Power MOSFET

### General Description

The 3060K uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 5V. This device is suitable for use as a wide variety of applications.

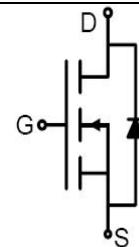
### Features

- VDS = 30V, ID = 60A  
RDS(ON) < 7mΩ @ VGS = 10V RDS(ON) < 12mΩ  
@ VGS = 5V
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

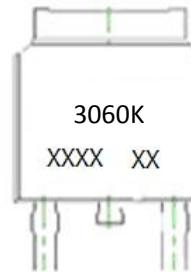
### Application

- PWM applications
- Load switch
- Power management

**100% UIS TESTED!**  
**100% ΔVds TESTED!**



Schematic Diagram



Marking and pin Assignment



TO-252(DPAK) top view

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
3060K	3060K	TO-252	325mm	16mm	2500

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	30	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25°C) <b>(Note 1)</b>	60	A
	Drain Current-Continuous(Tc=100°C)	38	A
IDM (pulse)	Drain Current-Continuous@ Current-Pulsed <b>(Note 2)</b>	250	A
PD	Maximum Power Dissipation(Tc=25°C)	65	W
	Maximum Power Dissipation(Tc=100°C)	33	W
EAS	Avalanche energy <b>(Note 3)</b>	120	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 175	°C



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**Table 2. Thermal Characteristic**

Symbol	Parameter	Typ	Max	Unit
R <sub>θJC</sub>	Thermal Resistance,Junction-to-Case	-	2.3	°C/W

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

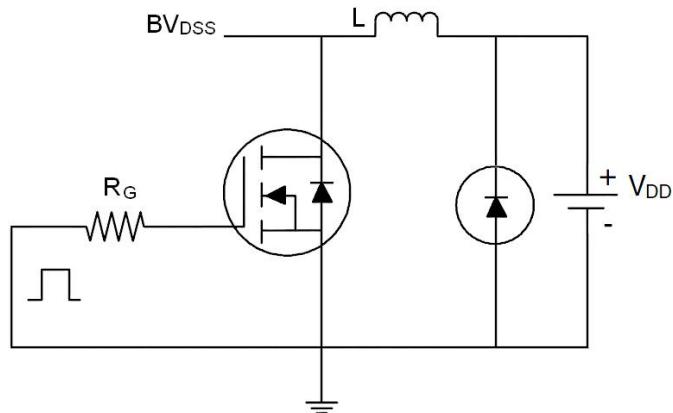
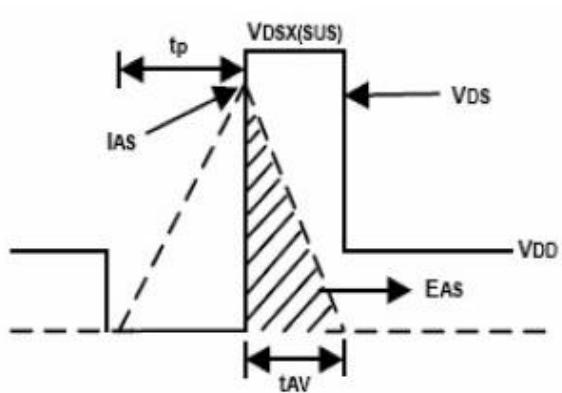
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V ID=250μA	30			V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V			1	μA
IGSS	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , ID=250μA	1.0	1.5	2.5	V
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, ID=20A		20		S
R <sub>DS</sub> (ON)	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, ID=20A (T <sub>c</sub> =25°C)		5.5	7.0	mΩ
		V <sub>GS</sub> =10V, ID=20A (T <sub>c</sub> =125°C)		7.3	11	mΩ
		V <sub>GS</sub> =5V, ID=15A		7.8	12	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V,		1450		pF
C <sub>oss</sub>	Output Capacitance			230		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			185		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		1.7		Ω
<b>Switching Times</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, RL=0.75Ω, R <sub>GEN</sub> = V <sub>GS</sub> =10V, V <sub>DS</sub> =25V, ID=14A		9		nS
t <sub>r</sub>	Turn-on Rise Time			26		nS
t <sub>d(off)</sub>	Turn-Off Delay Time			35		nS
t <sub>f</sub>	Turn-Off Fall Time			8		nS
Q <sub>g</sub>	Total Gate Charge			35		nC
Q <sub>gs</sub>	Gate-Source Charge			6		nC
Q <sub>gd</sub>	Gate-Drain Charge			12		nC
<b>Source-Drain Diode Characteristics</b>						
I <sub>SD</sub>	Source-Drain Current(Body Diode)				60	A
V <sub>SD</sub>	Forward on Voltage	V <sub>GS</sub> =0V, IS=20A			1.2	V

Notes 1.The maximum current rating is package limited.

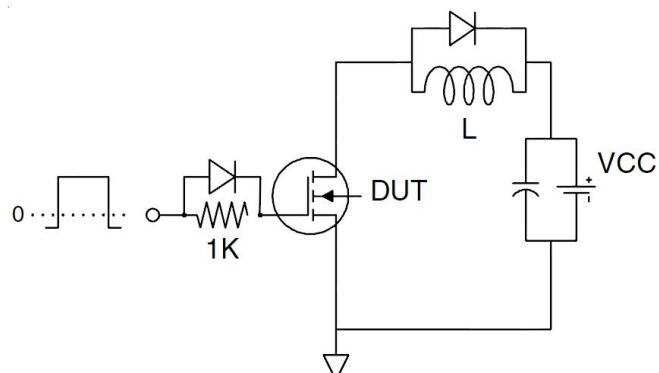
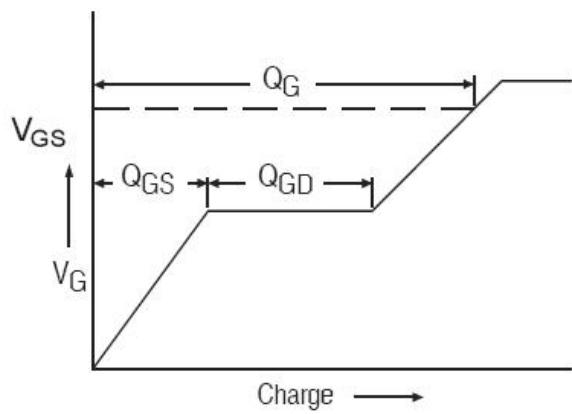
Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature Notes 3.EAS condition: TJ=25°C, VDD=15V, VG=10V, RG=25Ω

## Test Circuit

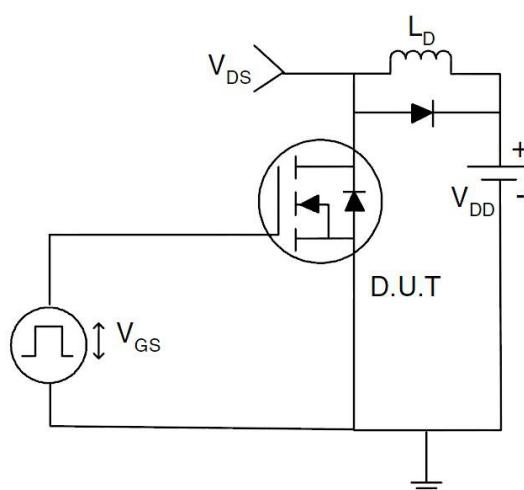
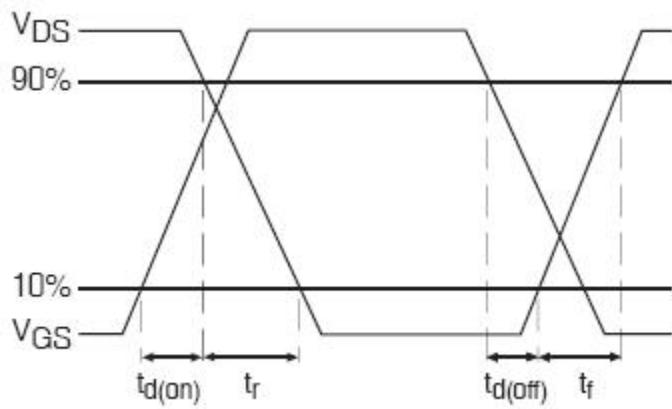
### 1) E<sub>AS</sub> Test Circuits



### 2) Gate Charge Test Circuit:



### 3) Switch Time Test Circuit:





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## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure 1. Output Characteristics

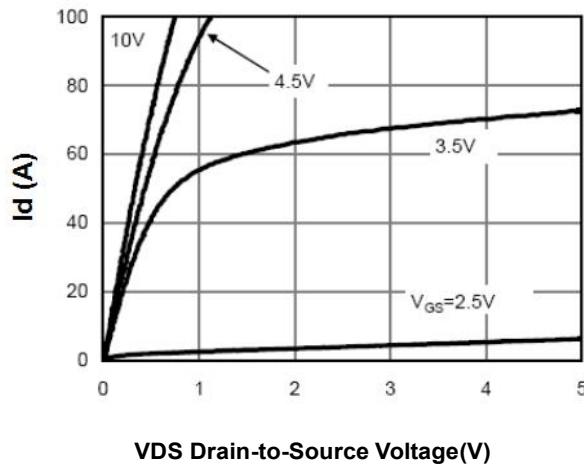


Figure 2. Transfer Characteristics

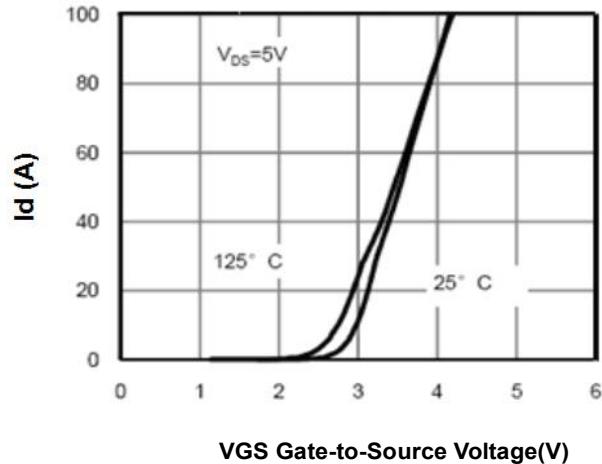


Figure 3. Max  $BV_{DSS}$  vs Junction Temperature

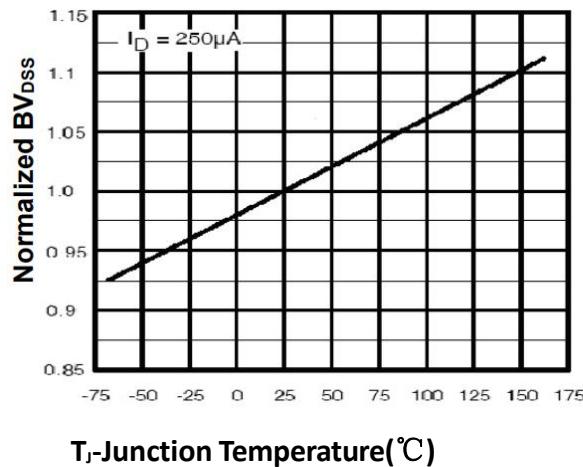


Figure 4. Drain Current

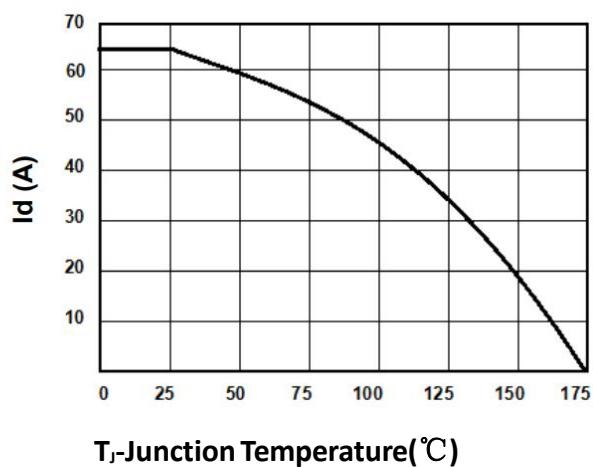


Figure 5.  $V_{GS(th)}$  vs Junction Temperature

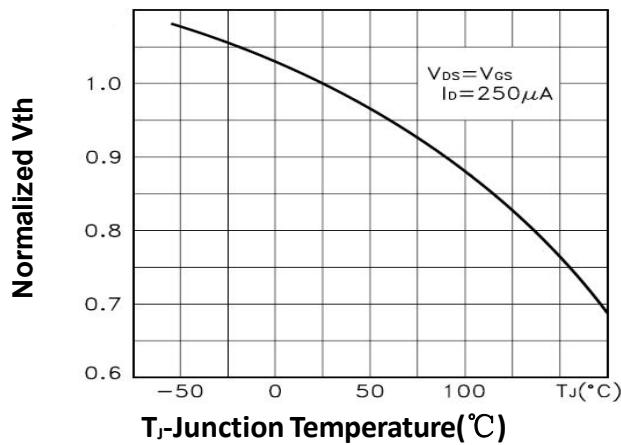
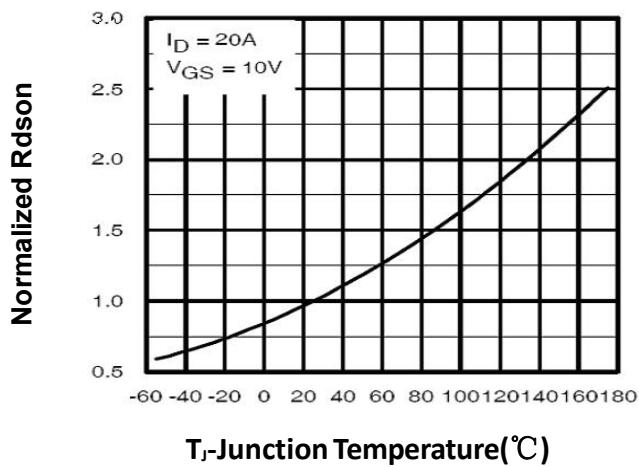


Figure 6.  $R_{DS(on)}$  vs Junction Temperature



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Figure 7. Gate Charge Waveforms

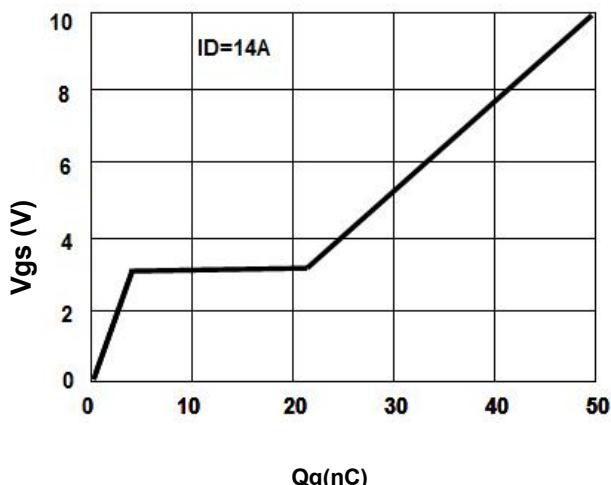


Figure 9. Body-Diode Characteristics

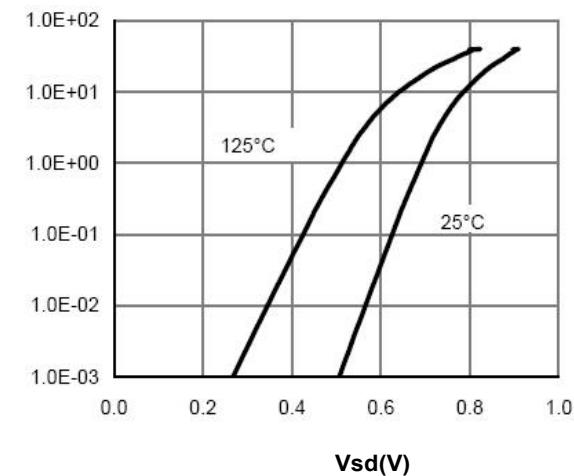


Figure 8. Capacitance

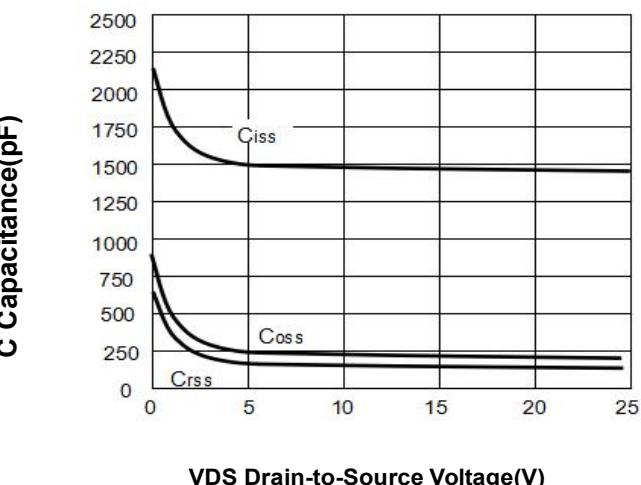


Figure 10. Maximum Safe Operating Area

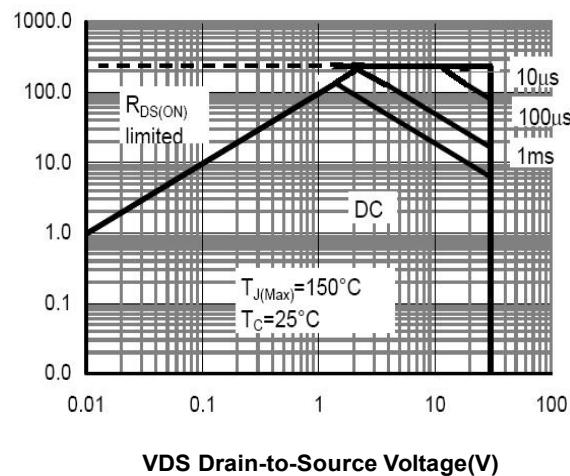
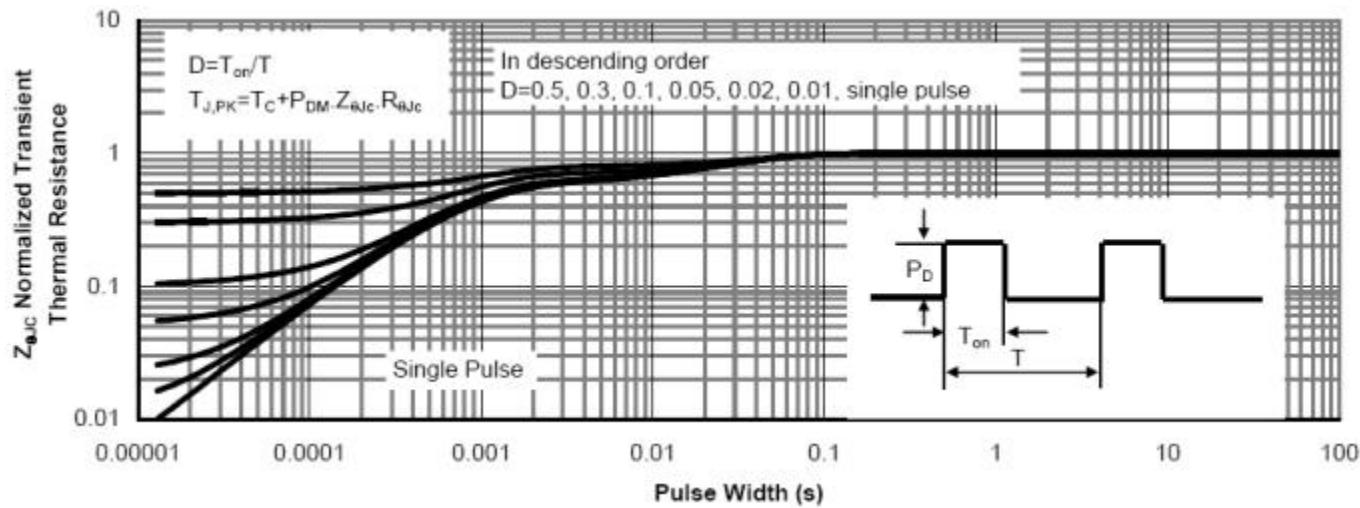


Figure 11. Normalized Maximum Transient Thermal Impedance





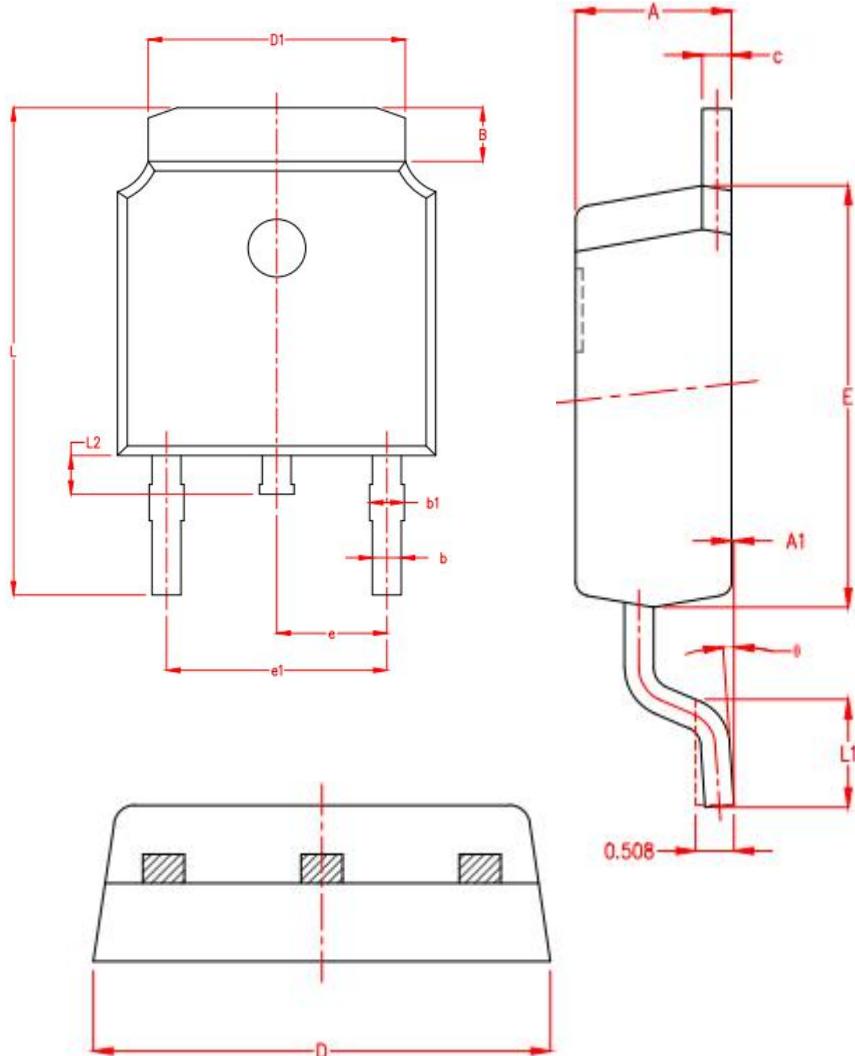
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### TO-252 Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.15	2.25	2.35
A1	0.00	0.06	0.12
B	0.96	1.11	1.26
b	0.59	0.69	0.79
b1	0.69	0.81	0.93
c	0.34	0.42	0.50
D	6.45	6.60	6.75
D1	5.23	5.33	5.43
E	5.95	6.10	6.25
e	2.286TYP.		
e1	4.47	4.57	4.67
L	9.90	10.10	10.30
L1	1.40	1.55	1.70
L2	0.60	0.80	1.00
θ	0°	4°	8°